

Features

- Planar chip junction.
- Fast response time, excellent clamping capability.
- Low incremental surge resistance.
- Typical failure mode is short for over-specified voltage or current.

Typical Applications

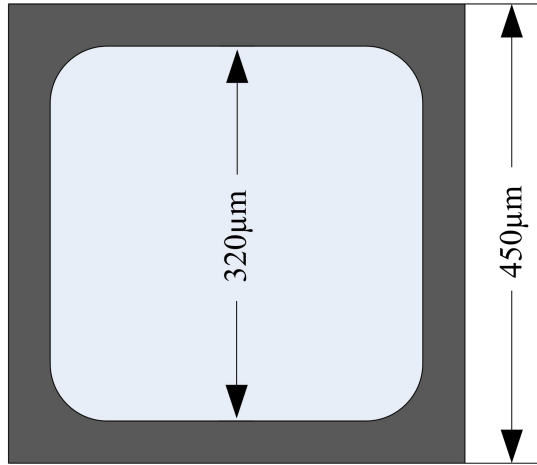
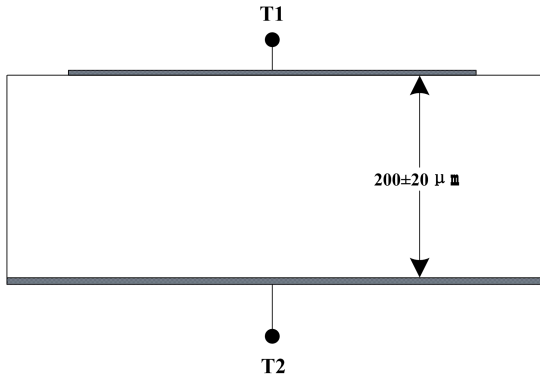
TVS devices are ideal for the protection of I/O interfaces, V_{CC} bus and other vulnerable circuits used in telecom, computer, industrial and consumer electronic applications.

Electrical Characteristics of CP Test ($T_a=25^\circ\text{C}$ unless otherwise noted)

Part number	V_{RWM} (V)	$V_{BR@I_T}$ (V)		I_T (mA)	$I_R@V_{RWM}$ (μA)	$**V_{C\text{ Max}}$ @ I_{PP} (V)	$**I_{PP}$ (A)	Chip construction
		Min	Max					
LM524ESDP30-0.45	24	26	30	1	0.5	35	30	Fig.1、 2

(** Obtained by the assigned assembly type SOD-323 per 8/20 μs waveform)

Physical Characteristics

Wafer size	5 inch
Wafer thickness	200±20μm
Die size	450μm*450μm (scribe line included)
Scribe line width	40μm typical
Front metallization	Al 4±1μm
Back metallization	Ag
Bonding area	 <p style="text-align: center;">Fig.1</p>
Die structure	 <p style="text-align: center;">Fig.2</p>

NOTICE

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